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Kind regards,

Team Nexperia



PDTA113EMB

PNP resistor-equipped transistor; R1 = 1 k Ω , R2 = 1 k Ω

Rev. 1 — 4 April 2012

Product data sheet

1. Product profile

1.1 General description

PNP Resistor-Equipped Transistor (RET) in a leadless ultra small DFN1006B-3 (SOT883B) Surface-Mounted Device (SMD) plastic package.

NPN complement: PDTC113EMB.

1.2 Features and benefits

- 100 mA output current capability
- Reduces component count
- Built-in bias resistors
- Reduces pick and place costs
- Simplifies circuit design
- AEC-Q101 qualified
- Leadless ultra small SMD plastic package
- Low package height of 0.37 mm

1.3 Applications

- Low-current peripheral driver
- Control of IC inputs
- Replaces general-purpose transistors in digital applications
- Mobile applications

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CEO}	collector-emitter voltage	open base	-	-	-50	V
I _O	output current		-	-	-100	mA
R1	bias resistor 1 (input)	T _{amb} = 25 °C	0.7	1	1.3	k Ω
R2/R1	bias resistor ratio		0.8	1	1.2	



2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	I	input (base)	 Transparent top view SOT883B (DFN1006B-3)	 sym003
2	G	GND (emitter)		
3	O	output (collector)		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PDTA113EMB	DFN1006B-3	Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.37 mm	SOT883B

4. Marking

Table 4. Marking codes

Type number	Marking code
PDTA113EMB	0001 1100



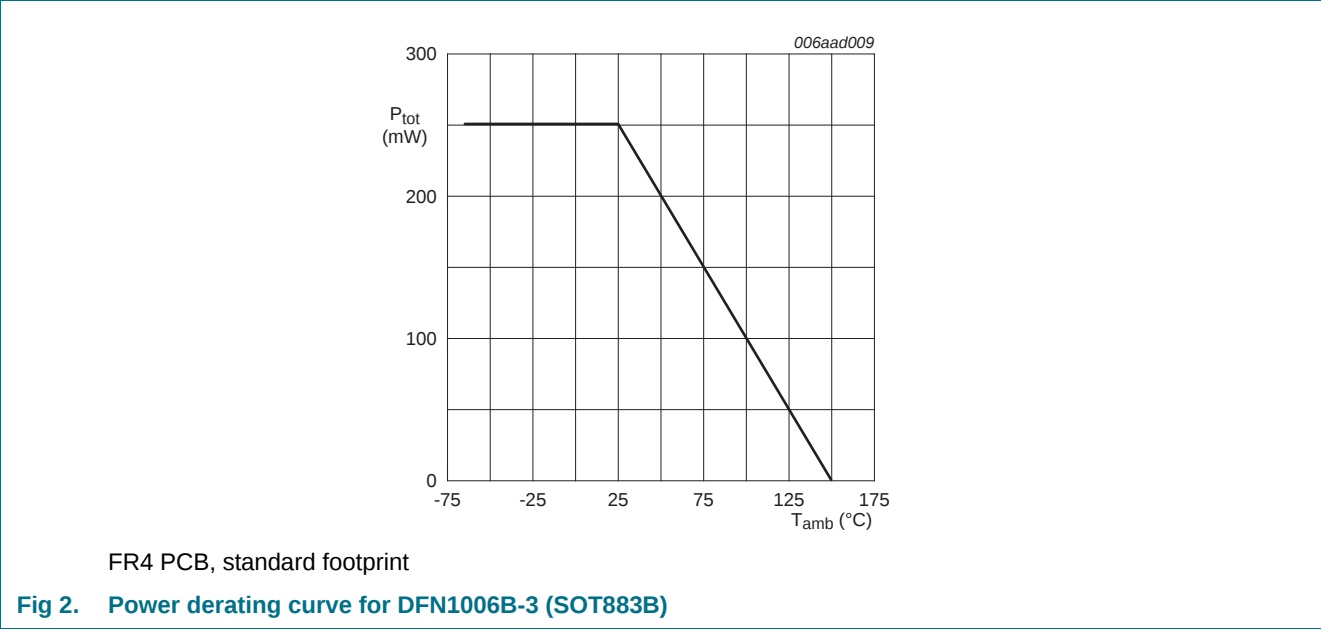
Fig 1. DFN1006B-3 (SOT883B) binary marking code description

5. Limiting values

Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CBO}	collector-base voltage	open emitter	-	-50	V
V _{CEO}	collector-emitter voltage	open base	-	-50	V
V _{EBO}	emitter-base voltage	open collector	-	-10	V
V _I	input voltage	positive	-	10	V
		negative	-	-10	V
I _O	output current		-	-100	mA
I _{CM}	peak collector current	pulsed; t _p ≤ 1 ms	-	-100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[1][2]	250	mW
T _j	junction temperature		-	150	°C
T _{amb}	ambient temperature		-65	150	°C
T _{stg}	storage temperature		-65	150	°C

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
[2] Reflow soldering is the only recommended soldering method.

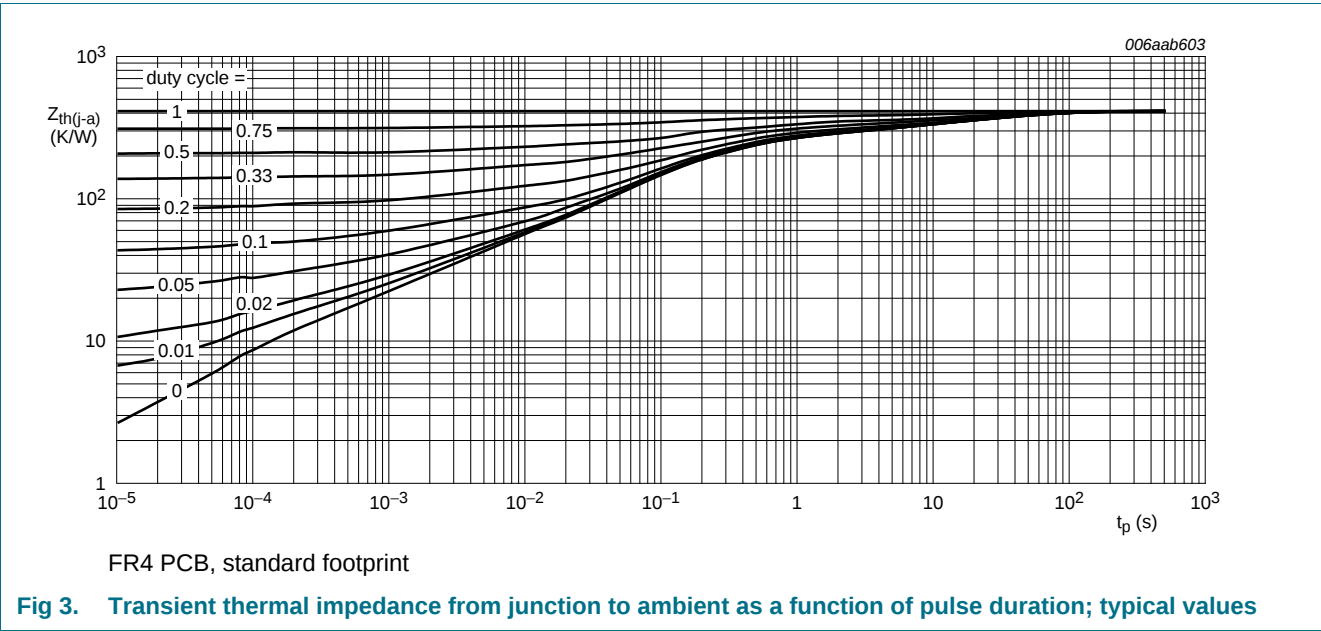


6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	-	-	500	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Reflow soldering is the only recommended soldering method.

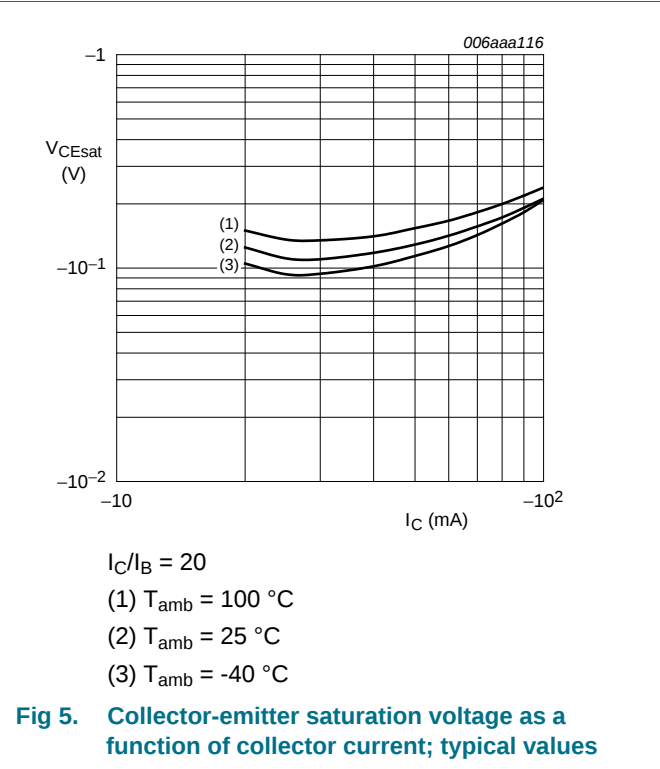
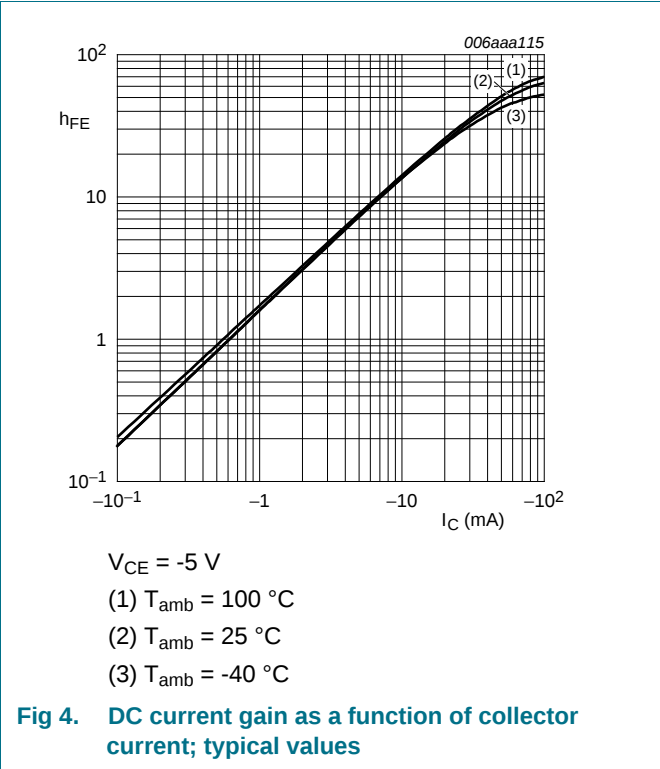


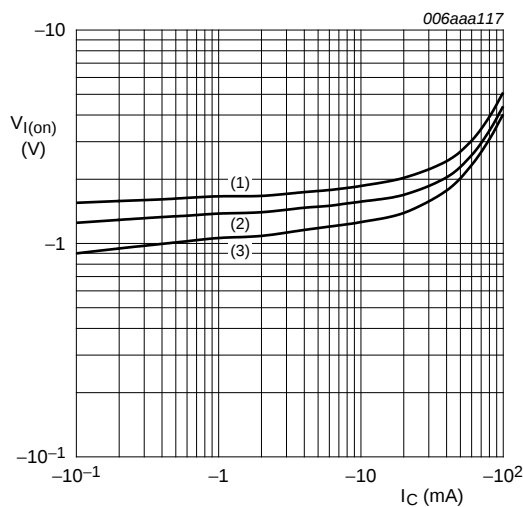
7. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	$V_{CB} = -50\text{ V}$; $I_E = 0\text{ A}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$	-	-	-100	nA
I_{CEO}	collector-emitter cut-off current	$V_{CE} = -30\text{ V}$; $I_B = 0\text{ A}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$	-	-	-1	μA
		$V_{CE} = -30\text{ V}$; $I_B = 0\text{ A}$; $T_j = 150\text{ }^{\circ}\text{C}$	-	-	-5	μA
I_{EBO}	emitter-base cut-off current	$V_{EB} = -5\text{ V}$; $I_C = 0\text{ A}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$	-	-	-4	mA
h_{FE}	DC current gain	$V_{CE} = -5\text{ V}$; $I_C = -40\text{ mA}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$	30	-	-	
V_{CEsat}	collector-emitter saturation voltage	$I_C = -30\text{ mA}$; $I_B = -1.5\text{ mA}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$	-	-	-150	mV
$V_{I(off)}$	off-state input voltage	$V_{CE} = -5\text{ V}$; $I_C = -100\text{ }\mu\text{A}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$	-	-1.3	-0.5	V
$V_{I(on)}$	on-state input voltage	$V_{CE} = -300\text{ mV}$; $I_C = -20\text{ mA}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$	-2	-1.7	-	V
R1	bias resistor 1 (input)	$T_{amb} = 25\text{ }^{\circ}\text{C}$	0.7	1	1.3	kΩ
R2/R1	bias resistor ratio		0.8	1	1.2	
C_C	collector capacitance	$V_{CB} = -10\text{ V}$; $I_E = 0\text{ A}$; $i_e = 0\text{ A}$; $f = 1\text{ MHz}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$	-	-	2	pF
f_T	transition frequency	$V_{CE} = -5\text{ V}$; $I_C = -10\text{ mA}$; $f = 100\text{ MHz}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$	[1]	180	-	MHz

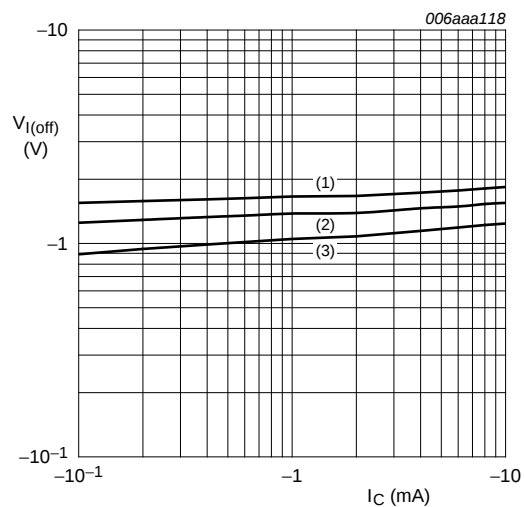
[1] Characteristics of built-in transistor.





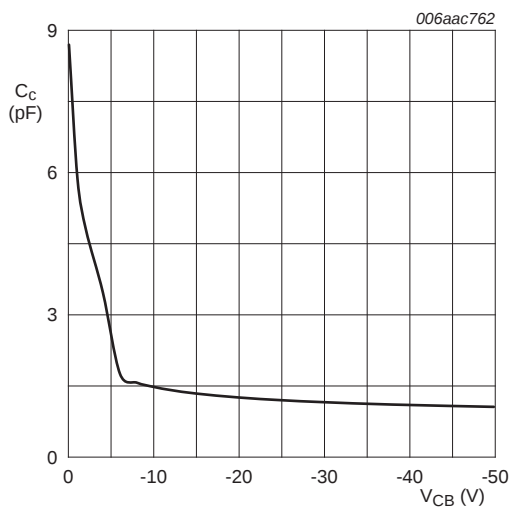
$V_{CE} = -0.3\text{ V}$
(1) $T_{amb} = -40\text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
(3) $T_{amb} = 100\text{ }^{\circ}\text{C}$

Fig 6. On-state input voltage as a function of collector current; typical values



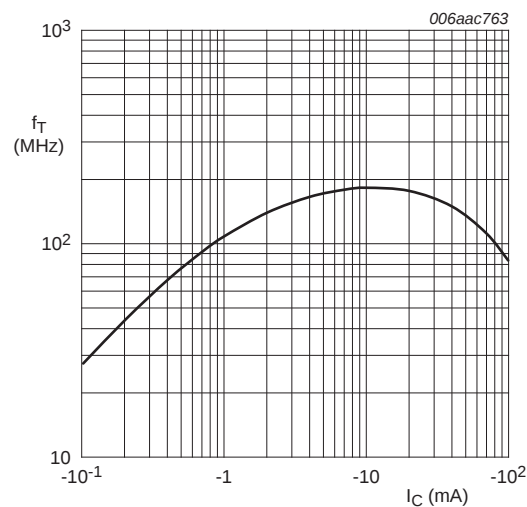
$V_{CE} = -5\text{ V}$
(1) $T_{amb} = -40\text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
(3) $T_{amb} = 100\text{ }^{\circ}\text{C}$

Fig 7. Off-state input voltage as a function of collector current; typical values



$f = 1\text{ MHz}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$

Fig 8. Collector capacitance as a function of collector-base voltage; typical values of built-in transistor



$V_{CE} = -5\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$

Fig 9. Transition frequency as a function of collector current; typical values of built-in transistor

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

9. Package outline

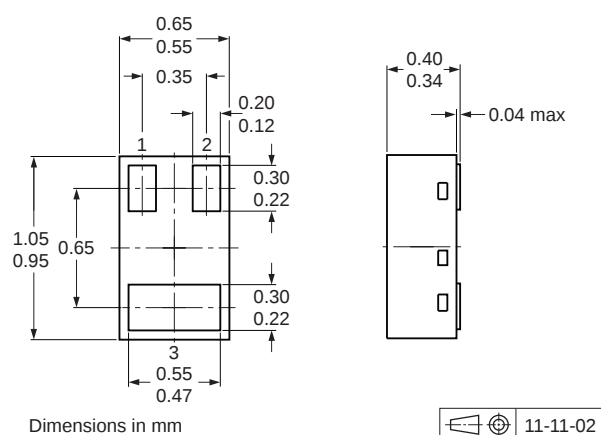
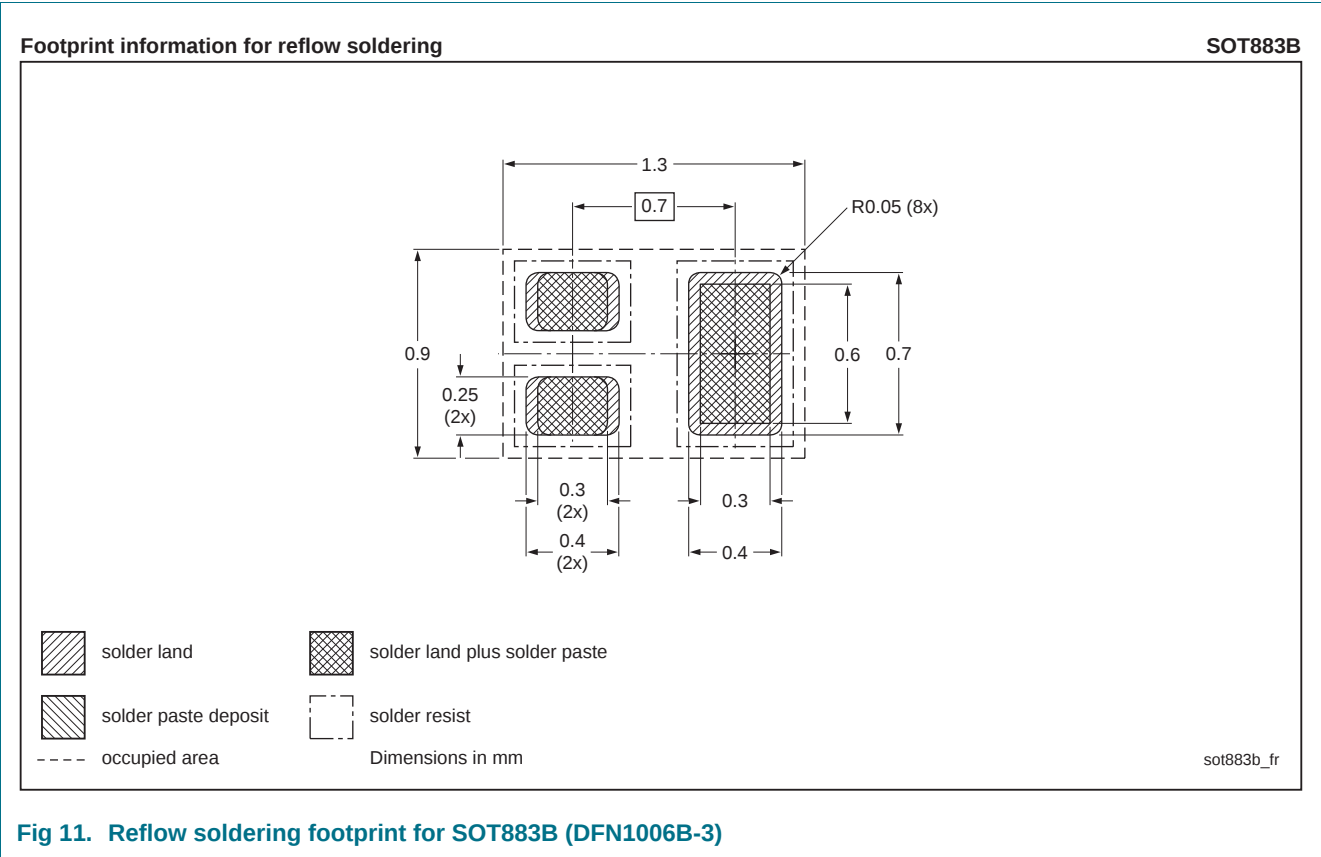


Fig 10. Package outline SOT883B (DFN1006B-3)

10. Soldering



11. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PDTA113EMB v.1	20120404	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1] [2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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